

FW: Nexperia Product Change Notification: CN-202510018F

Tempest, Emma (Farnell Global)

Product Change Notices

Regards

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Sent: 25 November 2025 02:57

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Subject: Nexperia Product Change Notification: CN-202510018F

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Product Change Notification

CN-202510018F

Issue date: 24 Nov 2025

Effective date: 08 Mar 2026

Dear etempest@farnell.com,

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Dual sourcing for back-end manufacturing of automotive products in SOT1220 package

Change
Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Details of this change

For the affected products, Nexperia is introducing dual sourcing regarding the assembly process. Currently, assembly for these products is performed only at ATGD. An additional Nexperia internal back-end site, ATSN, has now been qualified as

assembly location for the listed products. There will be no change in the product fit, form and function.

CN-202510018F_PCN-FORM-

Rev_5_1.xlsm: https://qcm.nexperia.com/Document/DOC-604917/CN-202510018F_PCN-FORM-Rev_5_1.xlsm

CN-2510018F_Delta-Qualification-Matrix-ZVEI-

5_1.xlsm: https://qcm.nexperia.com/Document/DOC-604916/CN-2510018F_Delta-Qualification-Matrix-ZVEI-5_1.xlsm

CN-

202510018FSelfQualificationReport.pdf: <https://qcm.nexperia.com/Document/DOC-604915/CN-202510018FSelfQualificationReport.pdf>

Why do we implement this change?

From implementation date on, Nexperia will have increased supply security provided by multiple assembly locations.

Identification of affected products

Top Side Marking

Product availability

Production

Planned first shipment: 08 Mar 2026

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Disposition of old products

Dual Sourcing, adding ATSN to supply chain.

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 24 Dec 2025. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

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CN-202510018F

Dual sourcing for back-end manufacturing of automotive products in SOT1220 package

Revision: 21 November 2025

Self Qualification Report

Document Information

Information	Content
Author	Suanne Kuhrau
Supplier	Nexperia
Document Number	CN-202510018F Self Qualification Report

Revision History

Revision Date	Description
21 November 2025	New document

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1. Subject

CN-202510018F contains detail information on the qualification of a second assembly location to produce automotive graded SOT1220 devices.

2. Introduction

In order to increase supply security for products in the package type SOT1220, Nexperia has qualified a second assembly location. This PCN covers the qualification and release of the automotive graded SOT1220 devices specified in Table 2 for the newly added assembly location.

Currently, our back-end site ATGD (Nexperia, Guangdong, China) is the single source location for the assembly processes of the affected products. With this change, we qualified our back-end site ATSN (Nexperia, Seremban, Malaysia) as additional assembly location. The production steps, used materials, in-line tests and control plans remain unchanged. There is no effect on fit, form and function of the affected products.

3. Changed assembly and final testing location

The following changes according to the ZVEI DeQuMa apply to all products shown in Table 2 (affected products list):

SEM-PA-18: Move all or parts of production to a different assembly site.

SEM-TF-01: Move of all or part of electrical wafer test and/or final test to a different test site.

Table 1: Back-end location: Assembly and testing

Current/ As is	New/ To be
Back-end (assembly and final testing) location: ATGD (Tianmei Industrial North, District A Section Huangjiang Town, Dongguan, 523750, China)	Back-end (assembly and final testing) location: ATSN (No. PT 12687, Tuanku Jaafar Industrial Park, 71450 Seremban, Negeri Sembilan, Malaysia)
	<u>Or</u> ATGD (Tianmei Industrial North, District A Section Huangjiang Town, Dongguan, 523750, China)

The additional assembly site Nexperia ATSN uses the same processes and materials as the current assembly site Nexperia ATGD. The Nexperia ATSN assembly site was founded in 1992 and has been assembling discrete semiconductors ever since.

The additional final testing site Nexperia ATSN uses the same test equipment and testing specifications as the current assembly site Nexperia ATGD. The Nexperia ATSN final testing site was founded in 1992 and has been testing discrete semiconductors ever since.

4. Affected product types

The product types to be released with this PCN are shown in Table 2.

Table 2: Affected product types

Product	12NC	Package Name	Type of change: additional assembly and final test location
			ATSN
BUK6D120-40E	9346 607 44115	SOT1220	•
BUK6D125-60E	9346 607 46115	SOT1220	•
BUK6D16-30E	9346 632 24115	SOT1220	•
BUK6D20-40E	9346 668 25115	SOT1220	•
BUK6D210-60E	9346 607 45115	SOT1220	•
BUK6D22-30E	9346 609 47115	SOT1220	•
BUK6D230-80E	9346 604 68115	SOT1220	•
BUK6D30-40E	9346 614 73115	SOT1220	•
BUK6D38-30E	9346 609 48115	SOT1220	•
BUK6D385-100E	9346 609 46115	SOT1220	•
BUK6D56-60E	9346 604 71115	SOT1220	•
BUK6D72-30E	9346 609 49115	SOT1220	•
BUK6D77-60E	9346 610 67115	SOT1220	•
BUK7D25-40E	9345 602 15115	SOT1220	•
BUK7D36-60E	9346 617 25115	SOT1220	•
BUK9D23-40E	9346 602 13115	SOT1220	•
PMPB55ENEA	9340 686 22115	SOT1220	•
PMPB85ENEA	9340 674 78115	SOT1220	•
PMPB95ENEA	9340 674 76115	SOT1220	•
BUK4D110-20P	9346 617 24115	SOT1220	•
	9346 617 24125	SOT1220	•
BUK4D16-20	9346 615 94115	SOT1220	•
	9346 615 94125	SOT1220	•
BUK4D38-20P	9346 614 84115	SOT1220	•
	9346 614 84125	SOT1220	•
	9346 614 84184	SOT1220	•

BUK6D120-60P	9346 603 43115	SOT1220	•
	9346 603 43184	SOT1220	•
BUK9D120-60P	9346 664 58115	SOT1220	•
PMPB10XNEA	9340 709 22115	SOT1220	•
PMPB12UNEA	9340 709 23115	SOT1220	•
PMPB13XNEA	9340 709 24115	SOT1220	•
PMPB15XPA	9340 709 26115	SOT1220	•
PMPB20XPEA	9340 709 27115	SOT1220	•
PMPB23XNEA	9346 602 18115	SOT1220	•
PMPB27EPA	9340 70932115	SOT1220	•
PMPB29XNEA	9340 709 25115	SOT1220	•
PMPB29XPEA	9340 709 28115	SOT1220	•
PMPB43XPEA	9340 709 29115	SOT1220	•
PMPB48EPA	9340 709 33115	SOT1220	•
BUK6D23-40E	9346 603 04125	SOT1220	•
	9346 603 04115	SOT1220	•
	9346 603 04184	SOT1220	•
BUK4D50-30P	934665701115	SOT1220	•
BUK6D81-80E	934661068115	SOT1220	•

5. Reliability test program

In line with AEC-Q101, AEC-Q006 and Nexperia General Quality Specification, the product types have been qualified. To validate the assembly quality and reliability performance an extensive qualification program has been performed.

5.1 Qualification strategy

The qualification plan has been developed based on FMEA risk assessment. Potential failures have been identified and were addressed in qualification.

5.2 Test vehicles

Table 3: Qualification leader types used for qualification

Product	Package	Assembly and Test Site
BUK6D43-40P	SOT1220	ATSN
BUK4D50-30P	SOT1220	ATSN
BUK4D60-30	SOT1220	ATSN
BUK6D23-40E	SOT1220	ATSN
BUK6D81-80E	SOT1220	ATSN
BUK4D50-30P	SOT1220	ATSN

6. Qualification plan

The qualification as reported in the summary below has been carried out to release the product type mentioned in this PCN.

Table 4: Qualification plan

Test Group A – Accelerated Environment Stress Tests

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
A1	PC Pre-conditioning	JEDEC/IPC J-STD-020, JESD22-A-113, TEST before and after PC	acc. to MSL 1	BUK6D43-40P BUK4D60-30 BUK6D23-40E BUK6D81-80E	- see notes -		0
		Notes: All qualification parts prior to tests #A2alt H ³ TRB, #A3 UHAST, #A4 TC/TCHT/TCDT, #A5 IOL/PTC and #C8 RSH.					
A2	HAST	JEDEC JESD22-A-110 T _A = 130 °C, RH = 85 %, VDS = see notes	96 hours	BUK6D43-40P BUK6D23-40E BUK6D81-80E	1 1 1	77	0

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
	Highly Accelerated Stress Test		192 hours	BUK6D43-40P BUK6D23-40E BUK6D81-80E	1 1 1	64	0
Notes: 13 samples per lot removed after 96h for analysis per AEC-Q006 (see Table 5)							
A2 alt	H³TRB High Humidity High Temperature Reverse Bias	JEDEC JESD22-A-101 T _A = 85 °C, RH = 85 %, V _{DS} = see notes	1000 hours	NA	NA	NA	NA
			2000 hours	NA	NA	NA	NA
	Notes: Omitted in lieu of alternative test, see test #A2.						
A3	UHAIST Unbiased HAST	JEDEC JESD22-A-118 T _A = 130 °C, RH = 85 %	96 hours	BUK6D43-40P BUK6D23-40E BUK6D81-80E	1 1 1	77	0
	Notes: -						
	A3 alt	AC Autoclave	JEDEC JESD22-A-102 T _A = 121 °C, RH = 100 %, p = 15 psig	96 hours	NA	N/A	N/A
Notes: Omitted in lieu of alternative test, see test #A3.							
A4		TC Temperature Cycling	JEDEC JESD22-A-104 Appendix 6 T = -65 °C to 150°C	1000 cycles	BUK6D43-40P BUK4D60-30 BUK6D23-40E	1 1 1	77
			2000 cycles	BUK6D43-40P BUK4D60-30 BUK6D23-40E	1 1 1	64	0
	Notes: 13 samples per lot removed after 1000h for analysis per AEC-Q006 (see Table 5).						
A4a	TCHT Temperature Cycling Hot Test	JEDEC JESD22-A-104 Appendix 6	1000 cycles	N/A	N/A	N/A	N/A
	Notes: See A4a alt.						
	A4a alt	TCDT Delamination Test	JEDEC JESD22-A-104 Appendix 6, J-STD-035	1000 cycles	N/A	N/A	N/A
Notes: Tests A4A and A4Aalt are not executed on Cu wire bonded products. Instead, follow the requirements in AEC-Q006, see Table 5							
A5		IOL Intermittent Operational Life	MIL-STD-750 Method 1037 T = 25 °C, ΔT _j ≥ 100 °C, t _{on} = t _{off} = 2 min	1000 hours	BUK6D43-40P BUK4D60-30 BUK6D23-40E	1 1 1	77
			2000 hours	BUK6D43-40P BUK4D60-30 BUK6D23-40E	1 1 1	77	0
	Notes: -						

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
A5 alt	PTC Power and Temperature Cycle	JESD22-A-105	1000 hours	N/A	N/A	N/A	N/A
Notes: Omitted in lieu of alternative test, see test # A5 (IOL).							

Test Group B – Accelerated Lifetime Simulation Tests

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
B1	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Condition A or M1039 Condition A T _j = T _{jmax} , V _{DS} = see notes	1000 hours	BUK6D43-40P	1	77	0
				BUK4D50-30P	1		
				BUK6D81-80E	1		
			2000 hours	BUK6D43-40P	1	76	0
BUK4D50-30P	1						
BUK6D81-80E	1						
Notes:		VDS: BUK6D43-40P=40V, BUK4D50-30P=28V, BUK6D81-80E =80V One sample per lot removed after 1000h for analysis per AEC-Q006 (see Table 5).					
B1a	ACBV AC blocking voltage	MIL-STD-750-1 M1040 Test condition A	1000 hours	N/A	N/A	N/A	N/A
B1b	SSOP Steady State Operational	MIL-STD-750-1 M1038 Condition B (Zeners)	1000 hours	N/A	N/A	N/A	N/A
B2	HTGB High Temperature Gate Bias	JEDEC JESD22-A-108	1000 hours	BUK6D43-40P	1	77	0
				BUK4D50-30P	1		
				BUK6D81-80E	1		
				Notes: -			

Test Group C – Package Assembly Integrity Tests

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
C1	DPA Destructive Physical Analysis	AEC-Q101-004 Section 4	-	BUK6D43-40P	1	2	0
		2 devices each after HAST		BUK6D23-40E	1		
				BUK6D81-80E	1		
		AEC-Q101-004 Section 4		BUK6D43-40P	1		
		2 devices each after TC		BUK4D60-30	1		
				BUK6D23-40E	1		
Notes: -							
C2	PD Physical Dimensions	JEDEC JESD22-B-100	-	BUK4D50-30P	1	30	0
Notes: -							
C3	WBP Wire Bond Pull Strength	MIL-STD-750-2 Method 2037 / AEC-Q006 (Cu-wire)	-	BUK6D43-40P	1	5	0
Notes: -							
C4	WBS Wire Bond Shear Strength	AEC-Q101-003, JEDEC JESD22-B116	-	BUK6D43-40P	1	5	0
Notes: -							
C5	DS Die Shear	MIL-STD-750-2 Method 2017	-	BUK6D43-40P	1	5	0
Notes: -							
C6	TS Terminal Strength	MIL-STD-750-2 Method 2036 evaluate lead integrity of through-hole leaded parts only	-	N/A	N/A	N/A	N/A
		Notes:	TS is required for through-hole leaded parts only. Reported parts are not through-hole leaded parts.				
C7	RTS Resistance to Solvents	JEDEC JESD22-B107 verify marking permanency	-	N/A	N/A	N/A	N/A
		Notes:	RTS is not required for laser etched parts or parts with no marking. Reported parts are laser etched parts.				
C8	RSH Resistance to Solder Heat	JEDEC JESD22-A-111 260 °C ± 5 °C	10 s	BUK4D50-30P	1	30	0
Notes: -							
C9	TR Thermal Resistance	JEDEC JESD24-3, 24-4, 24-6 as appropriate	-	BUK6D43-40P	1	10	0
Notes: -							
C10	SD Solderability	JEDEC J-STD-002	-	BUK4D50-30P	1	30	0
Notes: -							

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
C11	WG Whisker Growth Evaluation	AEC-Q005		----- according to AEC-Q005 -----			
	Notes:	No change of leadframe outside plating, leadframe material, leadframe dimensions or encapsulation process, therefore WG is not applicable					
C12	CA Constant Acceleration	MIL-STD-750-2 Method 2006	-	N/A	N/A	N/A	N/A
	Notes:	CA is required for hermetic packaged parts only. Reported package is not a hermetic package.					
C13	VVF Vibration Variable Frequency	JEDEC JESD22-B-103	-	N/A	N/A	N/A	N/A
	Notes:	VVF is required for hermetic packaged parts only. Reported package is not a hermetic package.					
C14	MS Mechanical Shock	JEDEC JESD22-B-104	-	N/A	N/A	N/A	N/A
	Notes:	MS is required for hermetic packaged parts only. Reported package is not a hermetic package.					
C15	HER Hermeticity	JEDEC JESD22-A-109	-	N/A	N/A	N/A	N/A
	Notes:	HER is required for hermetic packaged parts only. Reported package is not a hermetic package.					

Test Group D – Die Fabrication Reliability Tests

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
D1	DI Dielectric Integrity	AEC-Q101-004 Section 3	-	N/A	N/A	N/A	N/A
	Notes:	No change in die fabrication: No change of wafer fab processes or materials, no change of die design.					

Test Group E – Electrical Verification Tests

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
E0	EV External Visual	JEDEC JESD22-B101	-	All qualification parts submitting for testing.			0
Notes: Inspect part construction, marking and workmanship							

#	Stress	Test method	Duration	Tested part(s)	# of lots	Sample Size / lot	# of Fails
E1	TEST Pre- and Post-Stress Electrical Test	According to supplier’s standard specification	-	All qualification parts tested per the requirements of the appropriate part specification.			0
	Notes: Test is performed as specified in the applicable stress reference at room temperature.						
E2	PV Parametric Verification	Over part temperature range specified in data sheet.	-	BUK6D43-40P	1	25	0
				BUK4D50-30P	1		
				BUK4D60-30	1		
				BUK6D23-40E	1		
				BUK6D81-80E	1		
Notes:		For parametric verification data, sometimes circumstances may necessitate the acceptance of only one lot by the user.					
E3	ESDH ESD – HBM Characterization	AEC-Q101-001	-	N/A	N/A	N/A	N/A
	Notes: No change of wafer fab processes or materials, no change of die design.						
E4	ESDC ESD – CDM Characterization	AEC-Q101-005	-	N/A	N/A	N/A	N/A
	Notes:		Small packages are not able to hold enough charge and are therefore exempt of testing according to AEC-Q101-005.				
E5	UIS Unclamped Inductive Switching	AEC-Q101-004 Section 2	-	N/A	N/A	N/A	N/A
	Notes: No change of wafer fab processes or materials, no change of die design.						
E6	SC Short Circuit Characterization	AEC-Q101-006	-	N/A	N/A	N/A	N/A
	Notes: SC is required for smart power parts only. Reported parts are not smart power parts.						

Table 5: Analyses after test (according to Table 3b of AEC-Q006 Rev. A)

#	Analysis	Qualification Step	Tested part(s)	# of lots	Sample Size / lot	# of Fails
2	CSAM	Before preconditioning (#A1) of parts submitted to HAST (#A2 alt)	BUK6D43-40P	1	15	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		Before preconditioning (#A1) of parts submitted to TC (#A4) and IOL (#A5)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		

#	Analysis	Qualification Step	Tested part(s)	# of lots	Sample Size / lot	# of Fails
4	CSAM	Before preconditioning (#A1) of parts submitted to HAST (#A2 alt)	BUK6D43-40P	1	15	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		Before preconditioning (#A1) of parts submitted to TC (#A4) and IOL (#A5)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
8	CSAM	After 96h HAST (#A2)	BUK6D43-40P	1	15	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 1000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
9a	Ball + Stitch/Wedge pull	After 96h HAST (#A2)	BUK6D43-40P	1	3	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 1000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
9b	Ball shear	After 96h HAST (#A2)	BUK6D43-40P	1	3	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 1000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
10	Cross Section	After 96h HAST (#A2)	BUK6D43-40P	1	1	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 1000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
		After 1000h HTRB (#B1)	BUK6D43-40P	1		
			BUK4D50-30P	1		
			BUK6D81-80E	1		

#	Analysis	Qualification Step	Tested part(s)	# of lots	Sample Size / lot	# of Fails
13	CSAM	After 192h HAST (#A2)	BUK6D43-40P	1	15	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 2000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
14a	Ball + Stitch/Wedge pull	After 192h HAST (#A2)	BUK6D43-40P	1	2	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 2000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
14b	Ball shear	After 192h HAST (#A2)	BUK6D43-40P	1	2	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 2000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
15	Cross Section	After 192h HAST (#A2)	BUK6D43-40P	1	1	0
			BUK6D23-40E	1		
			BUK6D81-80E	1		
		After 2000c TC (#A4)	BUK6D43-40P	1		
			BUK4D60-30	1		
			BUK6D23-40E	1		
		After 2000h HTRB (#B1)	BUK6D43-40P	1		
			BUK4D50-30P	1		
			BUK6D81-80E	1		

7. Electrical and thermal performance

7.1 Electrical performance

Full electrical characterization over temperature range has been performed. Electrical parameters remain unchanged in specification and with the same distribution.

7.2 Thermal performance

Thermal parameters remain unchanged (in specification and with the same distribution).

8. Comparison of visual appearance

There is no change of visual appearance (within specification).

9. Traceability

Changed products can be identified by date code after implementation.

10. Conclusion

The products will not change functionally. Nexperia does not anticipate any negative impact on fit, form, function, and reliability.

11. Legal Disclaimer

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